

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A device comprising:
a first portion of an inductor disposed in a first layer of a multilayer substrate;
a second portion of the inductor disposed in a second layer of the multilayer substrate, the second portion coupled at a plurality of locations to the first portion; and
a shielding plane disposed between the first portion and the second portion.
2. (Original) A device according to Claim 1, wherein the shielding plane comprises a ground plane.
3. (Original) A device according to Claim 1, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.
4. (Withdrawn) A device according to Claim 1, further comprising:
a third portion of the inductor disposed in a third layer of the multilayer substrate, the third portion coupled to the second portion; and
a second shielding plane disposed between the second portion and the third portion.
5. (Original) A device according to Claim 1, wherein the inductor comprises a spiral turn inductor.

6. (Currently Amended) A device according to Claim 1, further comprising:

a plurality of vias to couple the first portion to the second portion.

7. (Currently Amended) A device according to Claim 1, further comprising:

a plurality of pin-through holes to couple the first portion to the second portion.

8. (Original) A device according to Claim 1, further comprising:

a dielectric disposed between the first layer and the shielding plane and between the second layer and the shielding plane.

9. (Currently Amended) A method comprising:

fabricating a first layer of a multilayer substrate comprising a first portion of an inductor;

fabricating a second layer of the multilayer substrate shielding plane above the first layer, ~~the second layer comprising a shielding plane~~; and

fabricating a third-second layer of the multilayer substrate above the second ~~layer~~ shielding plane, the third-second layer comprising a second portion of the inductor,

wherein ~~the second layer comprises a coupling to electrically couple the first portion of the inductor to the second portion of the inductor~~ the first portion is coupled to the second portion at a plurality of locations.

10. (Original) A method according to Claim 9, wherein the shielding plane comprises a ground plane.

11. (Original) A method according to Claim 9, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

12. (Withdrawn) A method according to Claim 9, further comprising:
fabricating a fourth layer of the multilayer substrate above the third layer, the fourth layer comprising a second shielding plane; and
fabricating a fifth layer of the multilayer substrate above the fourth layer, the fifth layer comprising a third portion of the inductor,
wherein the fourth layer comprises a second coupling to electrically couple the second portion of the inductor to the third portion of the inductor.

13. (Withdrawn) A system comprising:
an integrated circuit package comprising:
a first portion of an inductor disposed in a first layer of the integrated circuit package;
a second portion of the inductor disposed in a second layer of the integrated circuit package, the second portion coupled to the first portion; and
a shielding plane disposed between the first portion and the second portion;
and
a double data rate memory in communication with the integrated circuit package.

14. (Withdrawn) A system according to Claim 13, further comprising:
an integrated circuit die coupled to the integrated circuit package, the integrated circuit package to transmit data between the integrated circuit die and the memory.

15. (Withdrawn) A system according to Claim 13, wherein the shielding plane comprises a ground plane.

16. (Withdrawn) A system according to Claim 13, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

17. (Withdrawn) A system according to Claim 13, further comprising:
a third portion of the inductor disposed in a third layer of the multilayer substrate, the third portion coupled to the second portion; and
a second shielding plane disposed between the second portion and the third portion.